

Sir:

Transmitted herewith for filing is the Patent Application of:

Inventor: SYUN-MING JANG AND MING-HSIN HUANG

For: HARD MASKING METHOD FOR FORMING PATTERNED OXYGEN CONTAINING PLASMA ETCHABLE LAYER

Enclosed are:

- ☒ 2 sheets of formal drawing(s).  
☒ An assignment of the invention to Taiwan Semiconductor Manufacturing Company  
☐ An associate power of attorney

The filing fee has been calculated as shown below:

	(Col. 1)	(Col. 2)	OTHER THAN A SMALL ENTITY	
FOR:	NO. FILED	NO. EXTRA	RATE	FEE
BASIC FEE				\$ 790.
TOTAL CLAIMS	16 -20=	0	x 22 =	\$ 0.
INDEP CLAIMS	2 -3=	0	x 82 =	\$ 0.
MULTIPLE DEPENDENT CLAIM PRESENTED			+ 260 =	
SUB TOTAL				\$ 790.
ASSIGNMENT				\$40.
TOTAL				\$ 830.

- ☒ Please charge my Deposit Account No. 19-0033 in the amount of \$ 830. A duplicate copy of this sheet is enclosed.
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- ☒ Any additional filing fees required under 37 CFR \$1.16.
- ☒ Any patent application processing fees under 37 CFR \$1.17.

Respectfully submitted,  
*George O. Saile*  
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